

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6135031

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KHALED AHMED	05/28/2020
ANUP PANCHOLI	05/28/2020
JOHN HECK	05/28/2020
THOMAS SOUNART	06/01/2020
HAREL FRISH	05/28/2020
SANSAPTAK DASGUPTA	05/28/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INTEL CORPORATION
<b>Street Address:</b>	2200 MISSION COLLEGE BOULEVARD
<b>City:</b>	SANTA CLARA
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16890937
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	asahagian@ghmip.com
<b>Correspondent Name:</b>	GREEN, HOWARD, & MUGHAL LLP
<b>Address Line 1:</b>	5 CENTERPOINTE DR.
<b>Address Line 4:</b>	LAKE OSWEGO, OREGON 97035
<b>ATTORNEY DOCKET NUMBER:</b>	01.AC8450-US
<b>NAME OF SUBMITTER:</b>	ADAM SAHAGIAN
<b>SIGNATURE:</b>	/Adam Sahagian/
<b>DATE SIGNED:</b>	06/03/2020
<b>Total Attachments: 12</b>	
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## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**Khaled Ahmed  
Anup Pancholi  
John Heck  
Thomas Sounart  
Harel Frish  
Sansaptak Dasgupta**

hereby sell, assign, and transfer to:

**Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Blvd. Santa Clara, CA. 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

### **III-N MULTICHIP MODULES AND METHODS OF FABRICATION**

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on June 02, 2020 as

United States Application Number 16/890,937 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

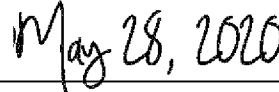
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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Khaled Ahmed



Date signed

\_\_\_\_\_  
Anup Pancholi

\_\_\_\_\_  
Date signed

\_\_\_\_\_  
John Heck

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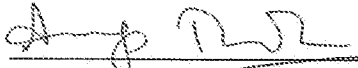
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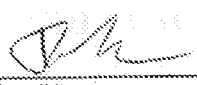
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*Thomas L. Sounart*  
Thomas Sounart

\_\_\_\_\_  
6/1/2020

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